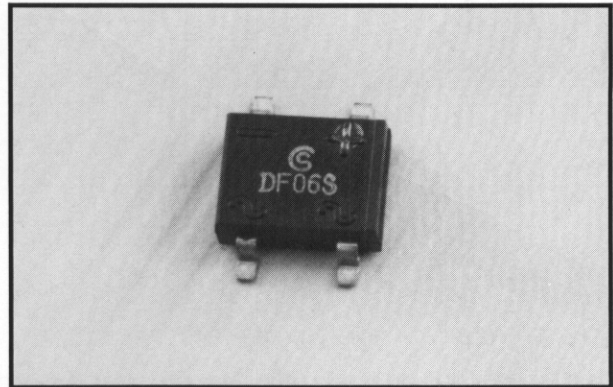


# DF005S Thru DF10S



## 1 AMP SURFACE MOUNT GLASS PASSIVATED SILICON BRIDGE



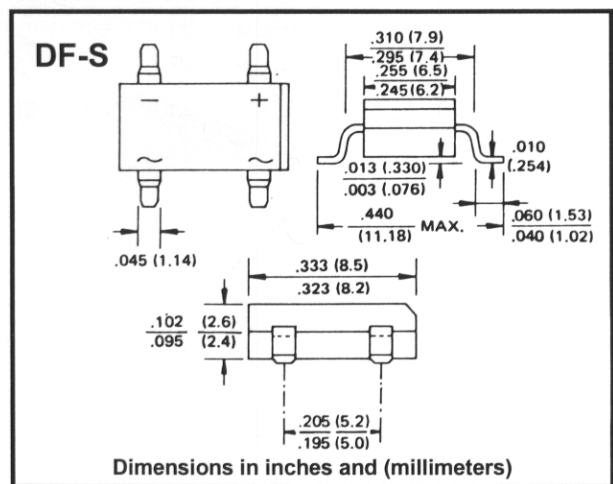
### FEATURES

- Rating to 1000V PRV
- Surge overload rating to 45 Amperes peak
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- UL recognized: File #E106441
- UL recognized 94V-O plastic material

### Mechanical Data

- Case: Molded plastic
- Leads: Tin plated copper
- Leads solderable per MIL-STD-202, Method 208
- Polarity: Symbols molded on body
- Weight: 0.02 ounce, 0.38 grams

### Outline Drawing



### Maximum Ratings & Characteristics

- Ratings at 25° C ambient temperature unless otherwise specified
- Single phase, half wave, 60Hz, resistive or inductive load
- For capacitive load, derate current by 20%

		DF005S	DF01S	DF02S	DF04S	DF06S	DF08S	DF10S	Units
Maximum Recurrent Peak Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	V
Maximum Average Forward Output Current @ T <sub>A</sub> = 40°C	I <sub>(AV)</sub>	1.0							A
Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave Superimposed On Rated Load	I <sub>FSM</sub>	50							A
Maximum DC Forward Voltage AT 1.0A DC	V <sub>F</sub>	1.1							V
Maximum DC Reverse Current @ T <sub>A</sub> = 25°C At Rated DC Blocking Voltage @ T <sub>A</sub> = 125°C	I <sub>R</sub>	10							μA
I <sup>2</sup> t Rating for Fusing (t < 8.3ms)	I <sup>2</sup> t	10.4							A <sup>2</sup> S
Typical Thermal Resistance per Element	C <sub>J</sub>	25							pF
Typical Thermal Resistance	R <sub>THJC</sub>	40							°C/W
Operating Temperature Range	T <sub>J</sub>	-55 to +125							°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150							°C